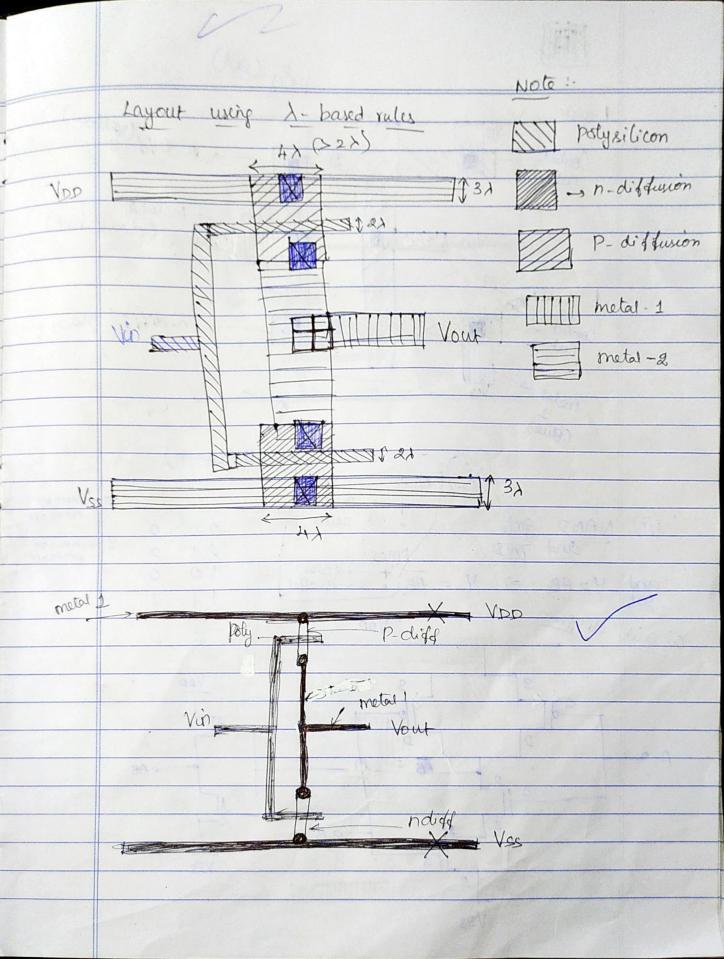
Stops for CMOS process: Draw othe motal (blue) VDD & Ves rails en parallel and creat a demarcation line in bow. Allowing enough space blow them to other CKT elements. 2) n-devices are placed below the demarcation line and p devices are placed above the demarcation line. 3) n&P devices are then connected using metal and contacts. 4) finally the remaining interconnections are mad & control signals and data ifp's are ædded. Note: * diffusion paths must not cross the demarcation * The metal should be used to connect 1 & P Jealines * ene must place chosses (x) on Vpp & Vac rails to represent the substrate and p-well connection respectively. * only metal & polysilicon Can accs the demorcation line * represent the Vss & Vop contact cross. one on Vss line for every 4 p-transistors. In one on Vss line for every 4 n-transistors.

* hetal lines as different layers (metal 1 & metal2) can cross are anthor. Contacting 2 metal lines requires a via . (1) write the CKT & stick diagram for cmos inverter supstate connection VAD metal D (blue) Vin = Vin . Vout pemaration S poty silicon. CKT diagram p-well connection VDD S D Vout oVour Vin. Gr poly



poly (Red) » o didd (yellow) 2 Vout (day blue) Contact · n-dist. (given) metal (Bue) P-well (Brown) NMUOS O-> PMOS ON -> Parallel rimes off series 00 1 -> mmos on 0 pmos pmosoff > seies 0 and parallel gate 9. alon ai aint VDP 3 VAD 3 D D AB e AB 9 VCS 3 VSS

